



Statement of Materials, Construction

LEAD-FREE -- 16L-SOICW -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.14156	Cu	7440-50-8	0.13790	30.59094	97.413
				Fe	7439-89-6	0.00333	0.73798	2.35
				Pb	7439-92-1	0.00004	0.00900	0.03
				P	7723-14-0	0.00012	0.02575	0.082
				Zn	7440-66-6	0.00018	0.03925	0.125
2	Die	Silicon Chip	0.00399	Si	7440-21-3	0.00397	0.88071	99.5
3	Die attach material	Conductive Epoxy	0.00051	Epoxy resin	Proprietary	0.00008	0.01697	15
				Silver	7440-22-4	0.00040	0.08938	79
				Aromatic Amine	Proprietary	0.00003	0.00679	6
4	Wire	Gold	0.00050	Au	7440-57-5	0.00050	0.11091	99.99
5	Lead Finish	Tin	0.00472	Sn	7440-31-5	0.00472	1.04707	100
6	Encapsulation	Epoxy Resin	0.2995	Fused Silica	60676-86-0	0.24020	53.28519	80.2
				Epoxy resin	Proprietary	0.02995	6.64404	10
				Phenol Novalac	9003-35-4	0.01498	3.32202	5
				Antimony trioxide	1309-64-4	0.00599	1.32881	2
				Brominated epoxy resin	68541-56-0	0.00749	1.66101	2.5
				Carbon Black	1333-86-4	0.00090	0.19932	0.3
Total Package weight			0.45078					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%